



COMO (Zhejiang) New Material Technology Co.,Ltd.

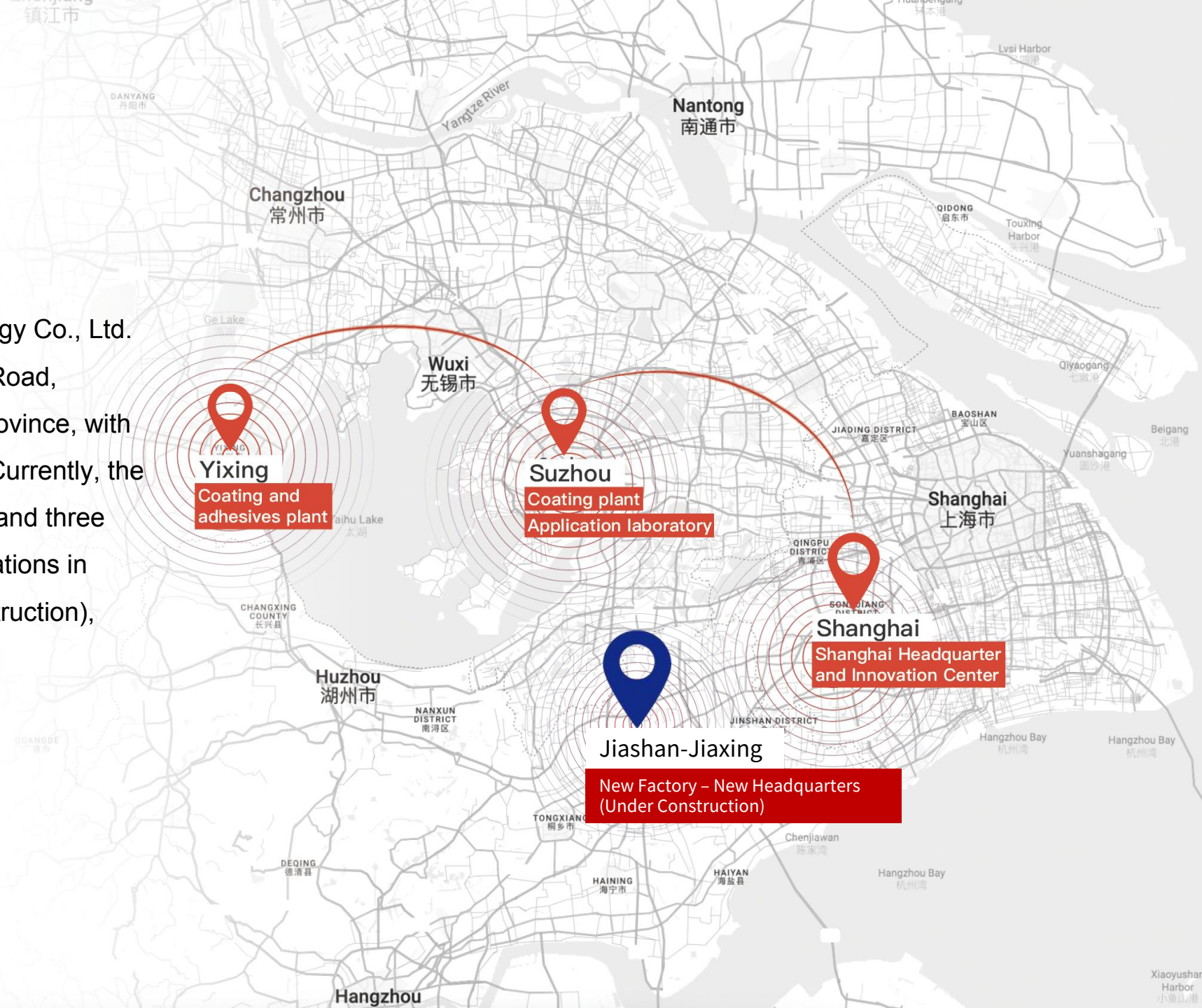


01 >

About COMO

About COMO

COMO (Zhejiang) New Material Technology Co., Ltd. is registered at Building A2, No. 8 Xinda Road, Jiashan County, Jiaxing City, Zhejiang Province, with a registered capital of RMB 62.5 million. Currently, the company operates two R&D laboratories and three affiliated manufacturing facilities, with locations in Shanghai, Jiashan (Zhejiang, under construction), Suzhou and Yixing.



About COMO

Shanghai Headquarter and Innovation Center



Coating plant, Suzhou/PAL

- 8000m² High-standard workshop
- 10,000 class clean room
- 1,000 class clean room for core coating areas
- VOC quota : 2.5 Ton/year





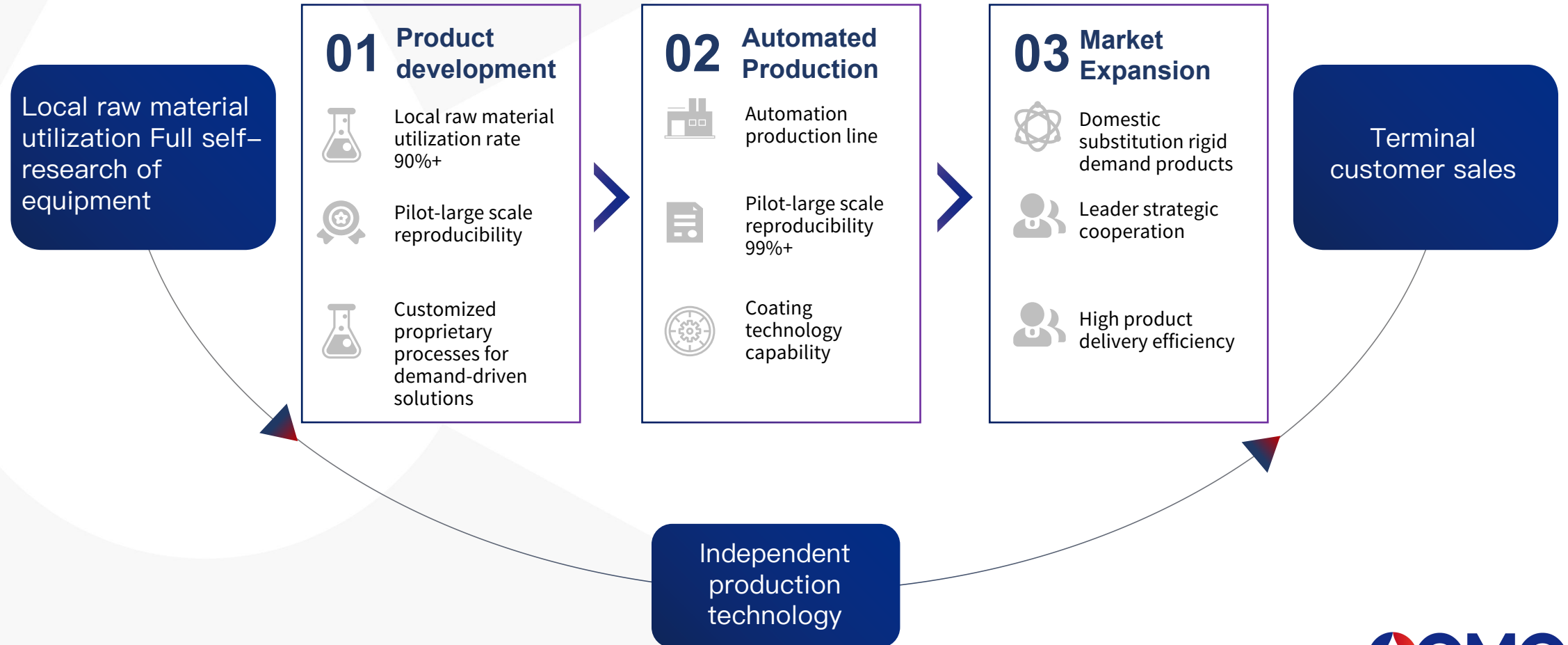
02 >

Strength of COMO



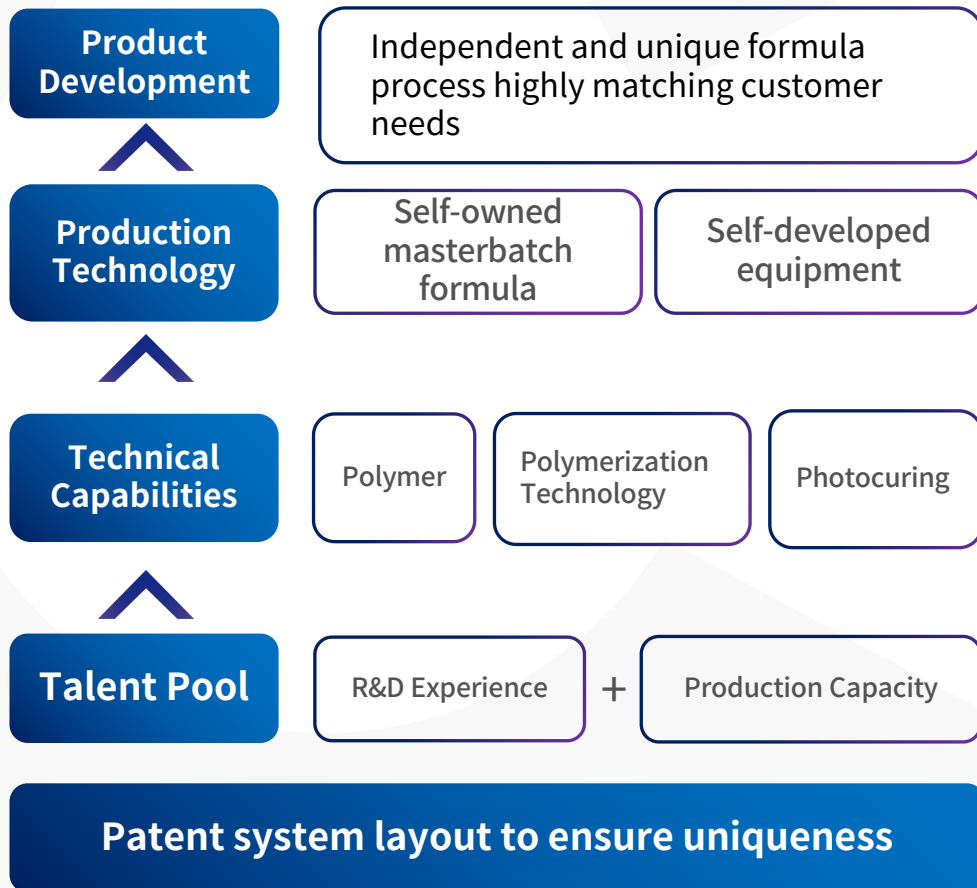
Technical strength

The company masters the complete smile curve of technology research and development - production - sales



Independent R&D Capability: The first domestic enterprise to achieve localization of both mother rubber raw materials and production equipment

01 Complete Positive R&D Capability



02 Masterbatch Formulation competence

Masterbatch Raw Materials

Localization of raw materials procurement and production

Self-developed synthetic formula

Hundreds of glue formulations cover the needs of various high-performance semiconductor chip production

03 Self-developed Functional Equipment

Reactor Equipment

Parameter design, precise quantitative solid-liquid addition, UV light curing control device, free radical copolymerization segmented polymerization device, automatic emergency control system.

Coating Machine

Automatic control recording of process parameters, automatic testing and feedback of adhesive layer thickness, detection and alarm recording of foreign objects appearance, and anti-error and anti-stupidity technology of equipment personnel.

Technical strength

Production Process Capability: Complete Product-Production Loop, Realizing Pilot-Large Scale Complete Replication

Technology-Production-Customer Simulation Experiment, Complete Production Loop

Technology Product Validation



Industrial Scale-Up

Pilot-Large Scale Production



High-Quality Delivery

Customer Simulation and Validation Capability

- **Product Development Source:** Market Research + Customer Joint R&D Reserve
- **Laboratory Formula Design:** DOE, QFD, D-FMEA, and other scientific methods to ensure the stability and reliability of formula implementation in the industry
- **Mid-scale Amplification Test:** The product performance undergoes multi-faceted evaluation, and the mid-to-large-scale intelligent control system remains consistent to ensure reproducibility.

- New Product Technology Reserve
- Control Development

Net 99%+ Replication of Pilot Line to Large Scale, Joint R&D Capability with Customers

Pilot Line:
Rapidly validates product design and production process



Glue Mixing Reaction Kettle



Pilot Coating Machine 600mm



Curing and Aging Chamber



Slitting Machine

Pilot-Large Scale Production :
High-Quality Delivery



Clean Room, Overall 10,000 Class, Local 1,000 Class



High Degree of Automation



Real-Time Quality Control and Guarantee

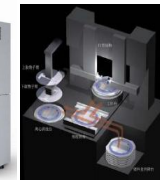
Strategic Collaborative Laboratory



Disco DF8540(BG)



DF6340/6450(DieSaw)



ESEC2100 (DA)

COMO

Technical strength

Advanced and complete testing equipment/capabilities

analytical equipment

Gel Permeation Chromatograph

Static Thermal Mechanical Analyzer

Differential Scanning Calorimetry Instrument

Thermogravimetric Analyzer

Dynamic Mechanical Analyzer

Fourier Transform Infrared Spectrometer

performance test

Tensile Testing Machine | Initial Tack

Tester | Dielectric Withstand Tester |

Resistance Tester | Viscosity Tester

High - temperature Incubator

High - low Temperature Test Chamber

Electronic Balance | High - power

Microscope

Reliability Testing

High - temperature Aging Chamber

Thermal Shock Test

UV Aging Test

Anchoring Damage Test



Technical strength

Como has industry-leading validation capabilities for Alpha Site (client-side simulation).

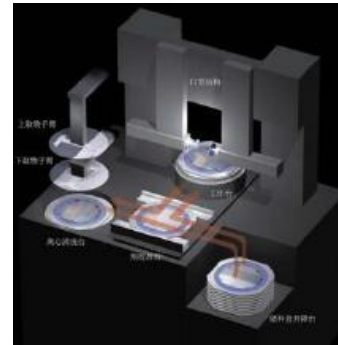
Strategic cooperation laboratories in Shanghai



Disco DF8540(BG)



DF6340/6450(DieSaw)



ESEC2100 (DA)

Technical strength

Comparison of Product Development Technologies and Production Capabilities at Home and Abroad: Como possesses the capabilities of all - round independent research and development and localization.

Raw materials					Production equipment		
Brand	Independent formula of glue	Localization of glue raw materials	Independent synthesis of glue	Localization of substrate materials	Design of glue synthesis equipment	Design of coating equipment	Independent production of coating
COMO	+	+	+	+	+	+	+
Domestic competing brands	-	-	-	-	-	-	+
Competing brands from abroad	+	-	+	-	+	+	+

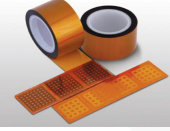
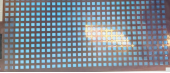
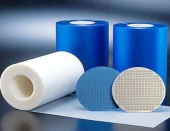
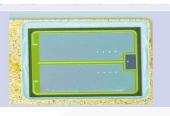
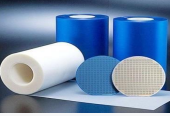




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COMO Products

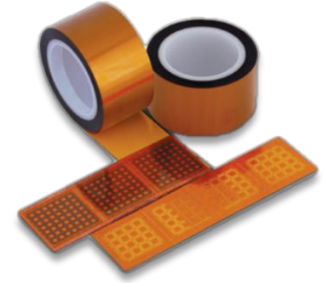
COMO products

Market		Product line	Core product	New product direction
Assembly EOL		 L/F backside tape	7303 SP1 standard post WB lamination 7303 TM1 high wettability post WB lamination 7303 XM1 plasma resistance & low residues 73251DAS pre-tape for QFN	> New requirement
		 Package saw tape	7216G Anti-ESD UV tape for normal singulation 7216GAS normal UV tape for normal singulation 7217G-ZJ ceramic substrate singulation 7217G-CS glass sawing	> New requirement
		 Molding release film	- MAC07605 series for C-molding - MAC07606C series for T-molding - MAC07805 series for panel molding	> New requirement
	★	 EMI tape	7306/7306AC for LGA packages 7370AS/7361AS/7386AS traditional process for BGA packages 75xxGAS lotus process for BGA packages	> New requirement
		 Dicing tape	8108 ultra small die for dicing 7108 non-UV dicing tape 7109G UV dicing tape 7209GAS UV dicing tape for SiC wafer	> DBG, SDBG New requirement
Assembly FOL		 BG tape	6212G standard BG tape 7212G RDL wafer BG tape 7218G thin wafer BG tape - PF270/PF280 bumping wafer BG tape	> New requirement
	★	 Pressure sintering tape	- MCA8905 series, multiple thickness - Pressure sintering tape for power module, 260degC, 5 min	> New requirement
FAB		 BG/BM tape	7509G chemicals resistance BGBM UV tape 8108 chemicals resistance BGBM non-UV tape	> New requirement

★ New market & new process

COMO products

Product-L/F tape (pre-tape/post-tape)



Pre-tape process

MTF-73251DAS-1451

- low warpage
- stable wire bond-ability
- low mold flash
- low residual
- Anti-ESD

Post-tape process

MTP-7303AS-SP1

- before-after heating adhesion (low-mid)
- Mold flash & residual balanceAnti-ESD

MTP-7303-TM1

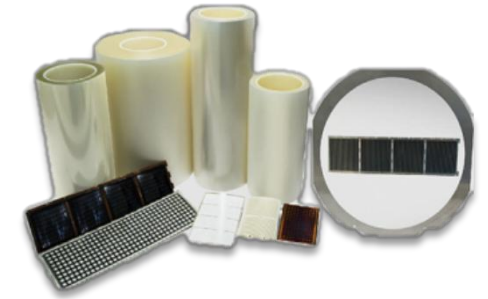
- before-after heating adhesion (high-high)
- Excellent mold flash control
- Anti-ESD

MTP-7303DAS-XM1

- before-after heating adhesion (mid-mid)
- Excellent residual control, plasma resistance
- Anti-ESD

COMO products

Product-Package saw tape



QFN,DFN,LGA,BGA

MGA-7216G (AS)

10um adhesive layer

- Optimized burr control
- no water seepage, easy to remove
- Good laser marking maintaining
- Anti-ESD

MGA-7217G (AS)

20um adhesive layer

- High adhesion
- No water seepage
- Easy to remove
- Anti-ESD

Ceramic

7217G-ZJ

- High adhesion
- No residual
- No ceramic remains

Glass

7217G-CS

- High adhesion
- No residual
- support laser sawing

COMO products

Product-Dicing tape



Standard non-UV

MUA-7108

- Mid adhesion
- high pickup UPH
- Burr free
- no residual
- Excellent chipping performance
- No die flying
- Support BSM wafer (pre-bake)

Standard UV

MUA-7109G

- High adhesion
- high pickup UPH
- Burr free
- no residual
- Excellent chipping performance
- No die flying

Ultra small die

NO.8108

- Super high adhesion
- High pickup UPH
- More than 3 months work life
- Support BSM wafer

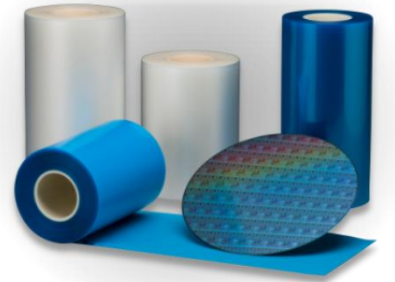
SiC wafer

MUA-7209G

- Super high adhesion
- Burr free
- no residual
- Excellent chipping performance
- No die flying
- Widely range for die size
- Excellent pickup performance

COMO products

Product-BG tape



Standard wafer	RDL wafer	Thin wafer	BSM wafer (Fab)	Standard Bumping wafer	High Bump height wafer
MOM-6212G • Support 100um wafer thickness • Non-BSM • no residual	MOM-7212G • Adapt to RDL wafer • Non-BSM • No residual	MOM-7218G • Support 50um thin wafer • Non-BSM • no residual • 8 inch TTV$\leq$5um • 12 inch TTV$\leq$6um	MKK-7509G UV MKK-8108 non-UV • No water seepage • Corrosion resistance • Easy to remove • No residual	MOM-JM-PF270 • Excellent bump protection (< 100um bump height) • Easy to remove no residual	MOM-JM-PF380 • Excellent bump protection (100~200um bump height) • Easy to remove no residual

COMO products

Product-EMI sputtering protection tape



LGA packages

MIE-7306

- Silica based
- No overflow
- Burr free

MIE-7306AC

- Acrylic
- Friendly for solderability
- No overflow
- Burr free

BGA traditional process

MIE-7370AS-600

- Friendly for solderability
- single side adhesive
- Lower overflow
- burr free

MIE-7316AS-550

MIE-7386AS-800

- Friendly for solderability
- Double side adhesive
- No overflow
- Burr free

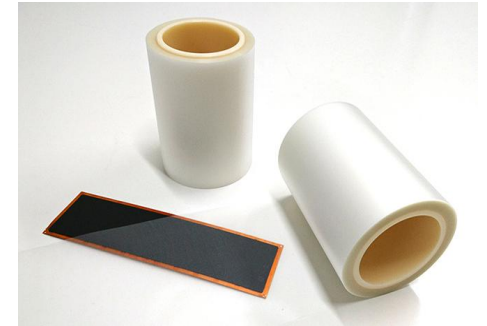
BGA lotus process

MIE-75xxGAS

- Non-silica based
- Friendly for solderability
- One tape to cover multiple package type
- Less processing
- No overflow
- Burr free

COMO products

Product-Molding release film



T-mold

MAC07705B

- Low roughness
- No wrinkle
- No mold flash
- No residual
- PFAS free

C-mold

MAC07505B

- Low roughness
- No wrinkle
- No residual
- PFAS free

MAC07605

- High roughness
- No wrinkle
- No residual
- PFAS free

Panel mold

MAC07805

- No wrinkle
- No residual
- PFAS free

COMO products

Product-Pressure sintering protection tape

PTFE pressure sintering protection tape

MCA80905

- Multiple thickness solutions (50um, 80um, 100um, 150um, 200um)
- Excellent die surface protection
- No residual & no discolor issue
- Long work-life
- Excellent stress resistance



COMO products

Our customers



The rankings do not distinguish between priority





THANKS